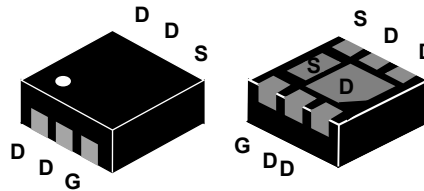
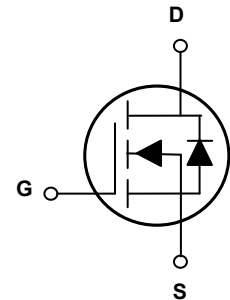


Main Product Characteristics

| | |
|---------------|-------------|
| $V_{(BR)DSS}$ | 40V |
| $R_{DS(ON)}$ | 24mΩ (Max.) |
| I_D | 20A |



DFN2x2-6L 2EP



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFB4024 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_A=25^{\circ}C$ unless otherwise specified)

| Parameter | Symbol | Rating | Unit |
|---|-----------------|-------------|------|
| Drain-Source Voltage | V_{DS} | 40 | V |
| Gate-Source Voltage | V_{GS} | ±20 | V |
| Drain Current-Continuous ($T_A=25^{\circ}C$) | I_D | 20 | A |
| Drain Current-Continuous ($T_A=70^{\circ}C$) | | 15 | A |
| Drain Current-Pulsed ¹ | I_{DM} | 41 | A |
| Power Dissipation ($T_C=25^{\circ}C$) | P_D | 14 | W |
| Power Dissipation – Derate above 25°C | | 0.12 | W/°C |
| Single Pulse Avalanche Energy ² | E_{AS} | 42 | mJ |
| Single Pulse Avalanche Current ² | I_{AS} | 16 | A |
| Maximun Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 62 | °C/W |
| Operating Junction Temperature Range | T_J | -55 To +150 | °C |
| Storage Temperature Range | T_{STG} | -55 To +150 | °C |

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|---|------------------------------|---|------|------|-----------|----------------------|
| On / Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 40 | - | - | V |
| BV_{DSS} Temperature Coefficient | $\Delta BV_{DSS}/\Delta T_J$ | Reference to 25°C , $I_D=1\text{mA}$ | - | 0.04 | - | V/ $^\circ\text{C}$ |
| Drain-Source Leakage Current | I_{DSS} | $V_{DS}=40V, V_{GS}=0V, T_J=25^\circ\text{C}$ | - | - | 1 | μA |
| | | $V_{DS}=32V, V_{GS}=0V, T_J=125^\circ\text{C}$ | - | - | 10 | μA |
| Gate-Source Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | - | - | ± 100 | nA |
| Static Drain-Source On-Resistance | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=5A$ | - | 20 | 24 | m Ω |
| | | $V_{GS}=4.5V, I_D=3A$ | - | 23 | 34 | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{GS}=V_{DS}, I_D=250\mu A$ | 1 | 1.8 | 2.5 | V |
| $V_{GS(th)}$ Temperature Coefficient | $\Delta V_{GS(th)}$ | | - | -3 | - | mV/ $^\circ\text{C}$ |
| Forward Transconductance | gfs | $V_{DS}=10V, I_D=3A$ | - | 3.6 | - | S |
| Dynamic and Switching Characteristics | | | | | | |
| Total Gate Charge ^{2,3} | Q_g | $V_{DS}=20V, I_D=3A, V_{GS}=4.5V$ | - | 18.5 | - | nC |
| Gate-Source Charge ^{2,3} | Q_{gs} | | - | 2.5 | - | |
| Gate-Drain Charge ^{2,3} | Q_{gd} | | - | 4.2 | - | |
| Turn-On Delay Time ^{2,3} | $t_{d(on)}$ | $V_{DD}=20V, R_G=25\Omega, V_{GS}=4.5V, I_D=1A$ | - | 6.4 | - | nS |
| Rise Time ^{2,3} | t_r | | - | 3.0 | - | |
| Turn-Off Delay Time ^{2,3} | $t_{d(off)}$ | | - | 27 | - | |
| Fall Time ^{2,3} | t_f | | - | 13 | - | |
| Input Capacitance | C_{iss} | $V_{DS}=15V, V_{GS}=0V, F=1\text{MHz}$ | - | 660 | - | pF |
| Output Capacitance | C_{oss} | | - | 65 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 37 | - | |
| Source-Drain Ratings and Characteristics | | | | | | |
| Continuous Source Current | I_S | $V_G=V_D=0V,$ Force Current | - | - | 20 | A |
| Pulsed Source Current | I_{SM} | | - | - | 41 | A |
| Diode Forward Voltage | V_{SD} | $V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$ | - | - | 1 | V |
| Reverse Recovery Time | t_{rr} | $T_J=25^\circ\text{C}, I_F=3A,$ $di/dt=100A/\mu\text{s}$ | - | 9 | - | ns |
| Reverse Recovery Charge | Q_{rr} | | - | 4.3 | - | nc |

Notes:

1. Repetitive rating; pulse width limited by max. junction temperature.
2. Pulse test: Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operation temperature.

Typical Electrical and Thermal Characteristic Curves

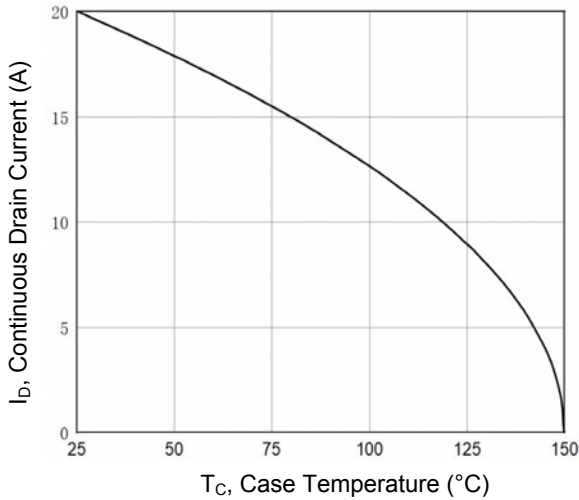


Figure 1. Continuous Drain Current vs. T_C

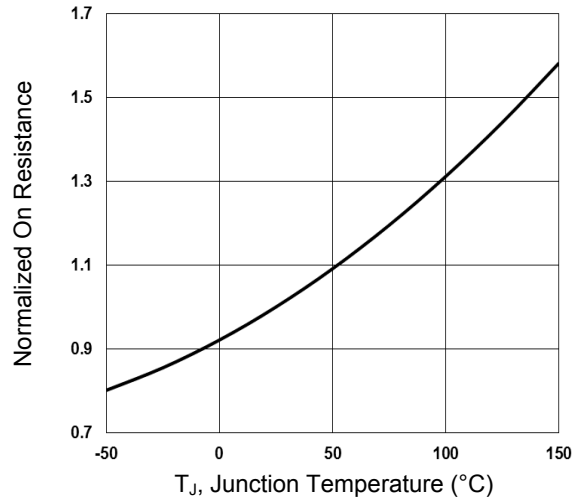


Figure 2. Normalized $R_{DS(ON)}$ vs. T_J

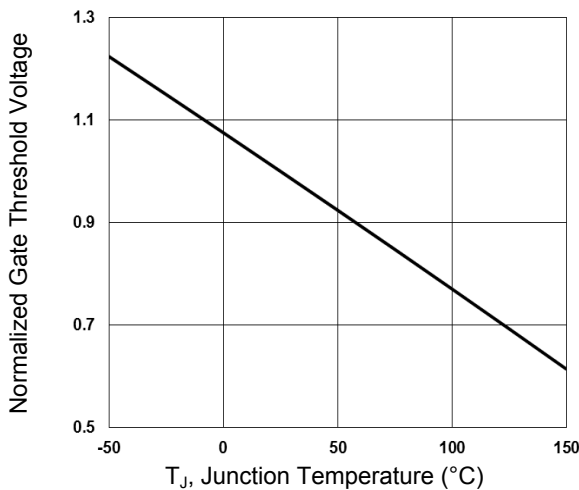


Figure 3. Normalized V_{th} vs. T_J

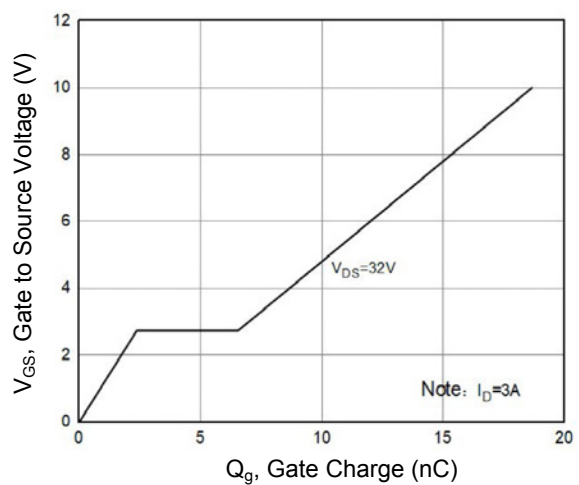


Figure 4. Gate Charge Waveform

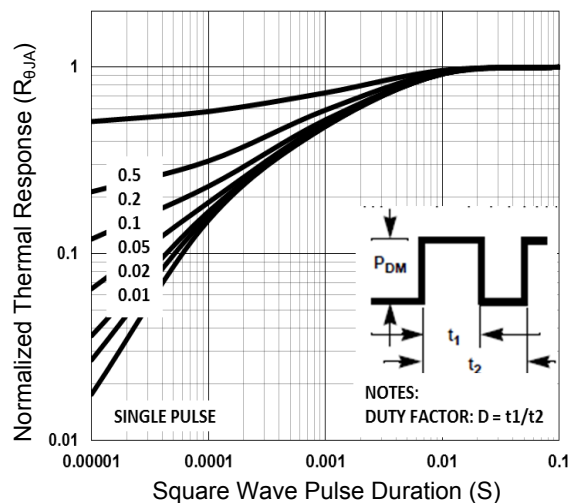


Figure 5. Normalized Transient Impedance

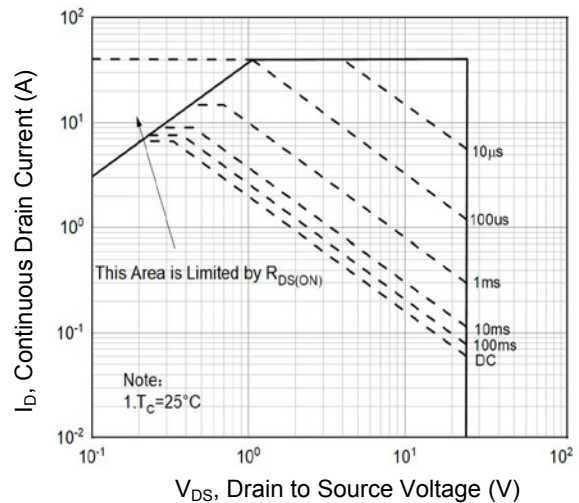
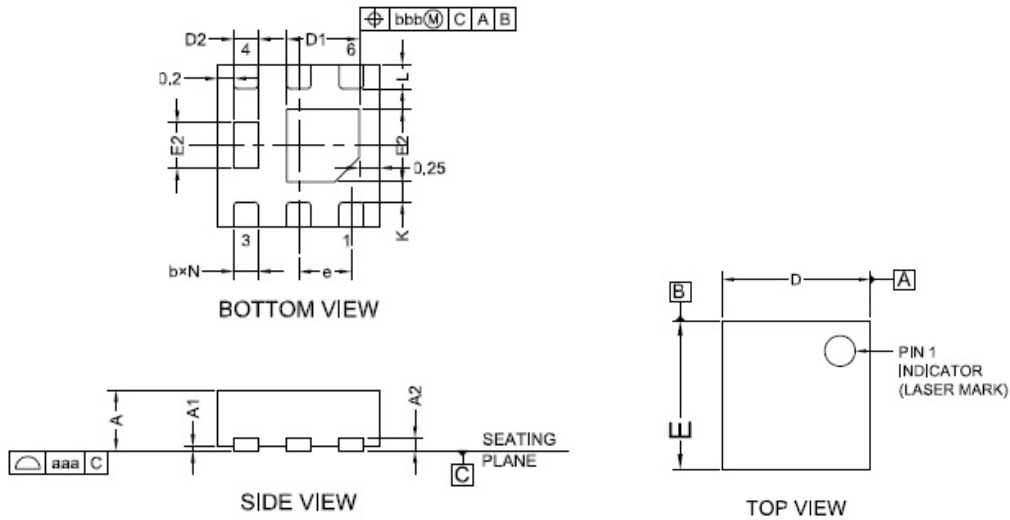


Figure 6. Maximum Safe Operation Area

Package Outline Dimensions (DFN2x2-6L 2EP)



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 0.500 | 0.600 | 0.020 | 0.024 |
| A1 | 0.000 | 0.050 | 0.000 | 0.002 |
| A2 | 0.152 REF | | 0.006 REF | |
| b | 0.250 | 0.350 | 0.010 | 0.014 |
| D | 1.950 | 2.050 | 0.077 | 0.081 |
| D1 | 0.800 | 1.000 | 0.031 | 0.039 |
| D2 | 0.250 | 0.350 | 0.010 | 0.014 |
| E | 1.950 | 2.050 | 0.077 | 0.081 |
| E1 | 0.800 | 1.000 | 0.031 | 0.039 |
| E2 | 0.460 | 0.660 | 0.018 | 0.026 |
| e | 0.650 BSC | | 0.026 BSC | |
| L | 0.250 | 0.350 | 0.010 | 0.014 |
| J | 0.400 BSC | | 0.016 BSC | |
| K | 0.200 MIN | | 0.008 MIN | |
| N | 6.000 | | 6.00 | |
| aaa | 0.080 | | 0.003 | |
| bbb | 0.100 | | 0.004 | |

Order Information

| Device | Package | Marking | Quantity | Carrier |
|----------|---------------|---------|-----------------|-------------|
| GSFB4024 | DFN2x2-6L 2EP | B4024 | 3,000pcs / Reel | Tape & Reel |

For more information, please contact us at: inquiry@goodarksemi.com